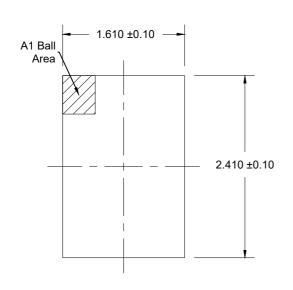
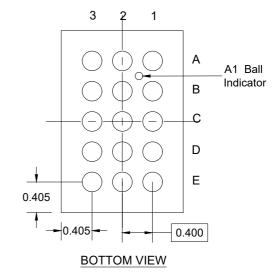


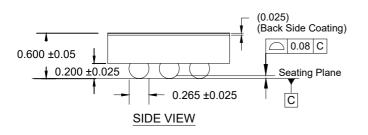


Package Code: AHG15D1 15-WLCSP 1.61 X 2.41 X 0.6 mm Body, 0.4mm Pitch

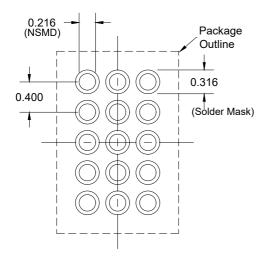
PSC-4904-01, Revision: 01, Date Created: Aug 2, 2022







**TOP VIEW** 



## RECOMMENDED LAND PATTERN

(PCB Top View, NSMD Design)

## NOTES:

- 1. JEDEC compatible.
- 2. All dimensions are in mm and angles are in degrees.
- 3. Use  $\pm 0.05$  mm for the non-toleranced dimensions.
- 4. Numbers in ( ) are for references only.
- 5. Pre-reflow solderball diameter is Ø0.25 mm.
- 6. UBM diameter is Ø0.24 mm.